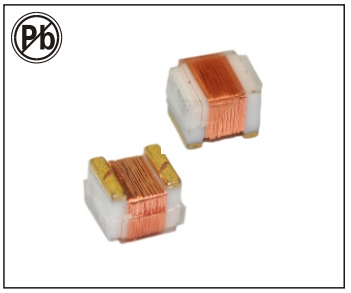
SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

AISC0402 SERIES



FEATURES:

- Multilayer monolithic construction yields high reliability
- High self-resonant frequency
- Excellentsolderability and heat resistance for either flow or reflow soldering

COMMON APPLICATIONS:

- High frequency circuits of telecommunication.
- Bluetooth
- Mobile phones such as GSM, CDMA, PDC, etc.
- Other High frequency circuits in general

ELECTRICAL CHARACTERISTICS:

Part Number	L(nH)	Tolerance (%)	Q Min	SRF (GHz) Min	DCR (Ω) Max	IDC (mA) Max
AISC0402-1N0☐	1.0@250MHZ	10	13@250MHZ	10.0	0.045	1360
AISC0402-2N2☐	2.2@250MHZ	10,5	18@250MHZ	6.00	0.07	960
AISC0402-2N7☐	2.7@250MHZ	10,5	15@250MHZ	6.00	0.12	640
AISC0402-3N3☐	3.3@250MHZ	10,5	20@250MHZ	6.00	0.066	840
AISC0402-3N9☐	3.9@250MHZ	10,5	20@250MHZ	6.00	0.066	840
AISC0402-4N7☐	4.7@250MHZ	10,5,2	18@250MHZ	4.50	0.2	640
AISC0402-5N6☐	5.6@250MHZ	10,5,2	20@250MHZ	4.80	0.083	760
AISC0402-6N8☐	6.8@250MHZ	10,5,2	23@250MHZ	4.80	0.26	680
AISC0402-8N2☐	8.2@250MHZ	10,5,2	25@250MHZ	4.40	0.1	680
AISC0402-10N☐	10@250MHZ	10,5,2	25@250MHZ	3.90	0.2	480
AISC0402-12N☐	12@250MHZ	10,5,2	25@250MHZ	3.60	0.12	640
AISC0402-15N☐	15@250MHZ	10,5,2	25@250MHZ	3.28	0.3	560
AISC0402-18N☐	18@250MHZ	10,5,2	25@250MHZ	3.10	0.23	420
AISC0402-22N☐	22@250MHZ	10,5,2	25@250MHZ	2.80	0.3	400
AISC0402-27N☐	27@250MHZ	10,5,2	24@250MHZ	2.48	0.52	280
AISC0402-33N☐	33@250MHZ	10,5,2	24@250MHZ	2.35	0.65	350
AISC0402-39N☐	39@250MHZ	10,5,2	25@250MHZ	2.10	0.75	200
AISC0402-47N☐	47@250MHZ	10,5,2	25@250MHZ	2.10	0.83	150
AISC0402-56N☐	56@250MHZ	10,5,2	25@250MHZ	1.76	0.97	100
AISC0402-68N☐	68@250MHZ	10,5,2	25@250MHZ	1.62	1.12	100
AISC0402-82N☐	82@250MHZ	10,5,2	25@250MHZ	1.26	1.7	50
AISC0402-R10☐	100@250MHZ	10,5,2	25@250MHZ	1.16	2	30
AISC0402-R12☐	120@250MHZ	10,5,2	25@250MHZ	1.10	2.2	30

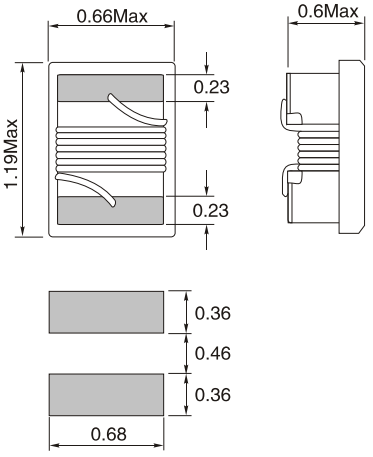
☐ G=±2%, J=±5%, K=±10%, M=±20%, N=±30%

TECHNICAL INFORMATION:

- Testing: (Equivalent acceptable)
  Inductance: HP4191A
  Q:HP4291A
  SRF:HP8753B
  RDC:measured @ 25℃
- Operating Temperature:
  Ceramic-55℃ to +125℃
- Pad metalization: Tungsten-nickel with gold flash
- Solder methods: Wave, Reflow, Vapor Phase
- Solderability: Max 260℃ for 10 seconds

PHYSICAL CHARACTERISTICS:

Dimensions:(mm)

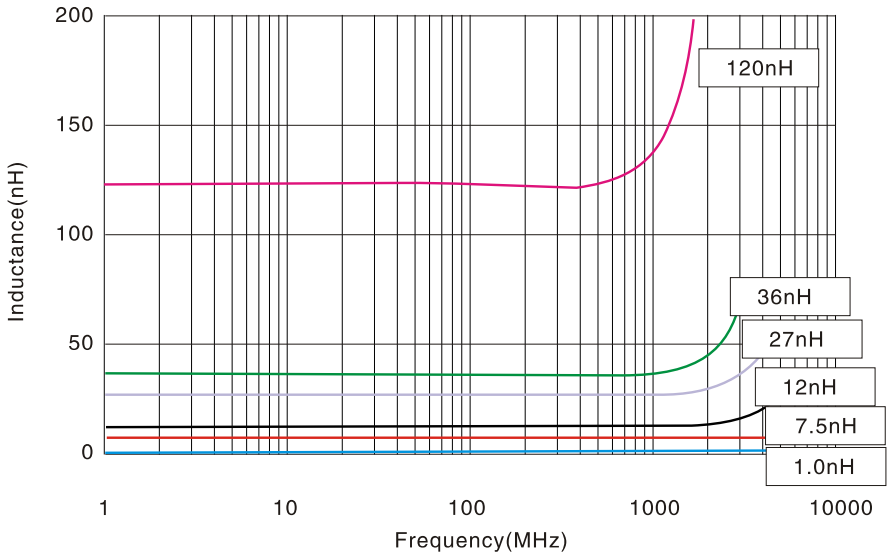


PCB LAYOUT

Winding

SURFACE-MOUNT WIRE WOUND CERAMIC CHIP INDUCTORS

Inductance Vs Frequency



Q Vs Frequency